

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT7163069

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	RELEASE OF SECURITY INTEREST AT REEL 050471 FRAME 0912	
<b>CONVEYING PARTY DATA</b>		
<b>Name</b>		<b>Execution Date</b>
BARCLAYS BANK PLC		01/07/2022
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	SMART EMBEDDED COMPUTING, INC.	
<b>Street Address:</b>	2900 S. DIABLO WAY, SUITE 190	
<b>City:</b>	TEMPE	
<b>State/Country:</b>	ARIZONA	
<b>Postal Code:</b>	85282	
<b>PROPERTY NUMBERS Total: 23</b>		
<b>Property Type</b>	<b>Number</b>	
Application Number:	15616257	
Application Number:	13724952	
Application Number:	14482295	
Application Number:	15148271	
Application Number:	14023521	
Application Number:	14219043	
Application Number:	15651023	
Application Number:	14141580	
Application Number:	14141594	
Application Number:	14140686	
Application Number:	14219051	
Application Number:	14219057	
Application Number:	14490169	
Application Number:	14490186	
Application Number:	14490226	
Application Number:	15624319	
Application Number:	15456034	
Application Number:	15455619	
Application Number:	15700561	
Application Number:	14254930	

PATENT

Property Type	Number
Application Number:	14251677
Application Number:	13741710
Application Number:	13757038

**CORRESPONDENCE DATA**

**Fax Number:** (800)914-4240

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

**Phone:** 800-713-0755

**Email:** Michael.Violet@wolterskluwer.com, ECarrera@cahill.com

**Correspondent Name:** CT CORPORATION

**Address Line 1:** 4400 EASTON COMMONS WAY

**Address Line 2:** SUITE 125

**Address Line 4:** COLUMBUS, OHIO 43219

<b>NAME OF SUBMITTER:</b>	ELAINE CARRERA
<b>SIGNATURE:</b>	/Elaine Carrera/
<b>DATE SIGNED:</b>	02/07/2022

**Total Attachments: 4**

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RECORDATION FORM COVER SHEET  
**PATENTS ONLY**

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)**

Barclays Bank PLC

**2. Name and address of receiving party(ies)**

Name: SMART EMBEDDED COMPUTING, INC.

Internal Address: \_\_\_\_\_

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

**3. Nature of conveyance/Execution Date(s):**

Execution Date(s) January 7, 2022

- ☐ Assignment ☐ Merger  
☐ Security Agreement ☐ Change of Name  
☐ Joint Research Agreement  
☐ Government Interest Assignment  
☐ Executive Order 9424, Confirmatory License  
☒ Other Release of Security Interest at Reel 050471 Frame 0912

Street Address: 2900 S. Diablo Way, Suite 190

City: Tempe

State: AZ

Country: USA Zip: 85282

Additional name(s) & address(es) attached? ☐ Yes ☒ No

**4. Application or patent number(s):**

☐ This document serves as an Oath/Declaration (37 CFR 1.63).

A. Patent Application No.(s)

See Schedule I

B. Patent No.(s)

See Schedule I

Additional numbers attached? ☒ Yes ☐ No

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Elaine Carrera, Senior Paralegal

Internal Address: \_\_\_\_\_

Street Address: c/o Cahill Gordon & Reindel LLP,  
32 Old Slip

City: New York

State: NY Zip: 10005

Phone Number: (212) 701-3365

Docket Number: \_\_\_\_\_

Email Address: ecarrera@cahill.com

**6. Total number of applications and patents involved: 23**

**7. Total fee (37 CFR 1.21(h) & 3.41) \$** \_\_\_\_\_

- ☐ Authorized to be charged to deposit account  
☐ Enclosed  
☐ None required (government interest not affecting title)

**8. Payment Information**

Deposit Account Number \_\_\_\_\_

Authorized User Name \_\_\_\_\_

**9. Signature:**

Elaine Carrera  
Signature

February 7, 2022

Date

Elaine Carrera

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

4

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

## RELEASE OF SECURITY INTEREST IN INTELLECTUAL PROPERTY

This RELEASE OF SECURITY INTEREST IN INTELLECTUAL PROPERTY (this "Release"), dated as of January 7, 2022 (the "Effective Date"), is made by Barclays Bank PLC, in its capacity as Administrative Agent (the "Agent"), in favor of the grantor parties identified on the signature page hereto (the "Grantors").

WHEREAS, pursuant to that certain Collateral Agreement, dated as of August 26, 2011, by and among the Agent, the Grantors and certain other parties thereto (as amended, amended and restated, or otherwise modified from time to time, the "Collateral Agreement"), the Grantors granted to the Agent, in its capacity as Agent, a security interest in and to certain collateral;

WHEREAS, pursuant to the Collateral Agreement, SMART Embedded Computing, Inc. executed and delivered a Patent Security Agreement, dated as of September 24, 2019, among the Administrative Agent and Grantor (the "SMART Embedded Computing Patent Security Agreement"), Grantor, by reference to the Collateral Agreement, reaffirmed its intent to grant the security interest to the Administrative Agent specifically in certain collateral (as that term is defined in the SMART Embedded Computing Patent Security Agreement, including the Patents set forth on Schedule I hereto);

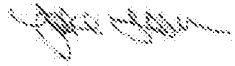
WHEREAS, the SMART Embedded Computing Patent Security Agreement was recorded with the United States Patent and Trademark Office on September 24, 2019 at Reel/Frame 050471/0912;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the Agent hereby agrees as follows:

1. Defined Terms. All capitalized terms used, but not otherwise defined herein, shall have the respective meanings ascribed in or otherwise referenced in the Collateral Agreement or the SMART Embedded Computing Patent Security Agreement, as applicable.
2. Release. The Agent, without representation or warranty of any kind, hereby releases, discharges, terminates and cancels all of its security interest in and to the Patent Collateral, including the patents and patent applications set forth Schedule I attached hereto, arising under the Collateral Agreement, the SMART Embedded Computing Patent Security Agreement and the Patent Succession Agreement. If and to the extent that the Agent has acquired any right, title or interest in and to the Patent Collateral, the Agent, without representation or warranty of any kind, hereby re-transfers, re-conveys and re-assigns such right, title or interest to the Grantors.
3. Termination. The Agent, without representation or warranty of any kind, terminates and cancels the SMART Embedded Computing Patent Security Agreement.
4. Further Assurances. The Agent agrees to take all further actions, and provide to the Grantors and their successors, assigns or other legal representatives, all such cooperation and assistance (including, without limitation, the execution and delivery of any and all documents or other instruments), reasonably requested by the Grantors, at the Grantors' sole cost and expense, to more fully and effectively effectuate the purposes of this Release.
5. Governing Law. This Release shall be governed exclusively under the laws of New York, without regard to conflicts of law or choice of law principles.

IN WITNESS WHEREOF, the Agent has caused this Release to be executed by its duly authorized representative as of the Effective Date:

**Barclays Bank PLC, acting in its capacity as Agent  
for the Lenders**



By: \_\_\_\_\_

Name: Jake Lam

Title: Assistant Vice President

**GRANTORS:**

**SMART EMBEDDED COMPUTING, INC.**

**SCHEDULE I**

**Patent Collateral**

**Release of Patent Security Agreement recorded September 24, 2019 at Reel/Frame  
050471/0912**

**PATENTS OWNED BY SMART EMBEDDED COMPUTING, INC.**

<b>Patent</b>	<b>Serial No.</b>	<b>Patent No.</b>
INTEGRATED THERMAL INSERTS AND COLD PLATE	15/616257	10039210
CONFIGURABLE COOLING FOR RUGGED ENVIRONMENTS	13/724952	Pending
TIME-DIVISION MULTIPLEXING DATA AGGREGATION OVER HIGH SPEED SERIALIZER/DESERIALIZER LANE	14/482295	10027600
METHOD AND SYSTEM OF SYNCHRONIZING PROCESSORS TO THE SAME COMPUTATIONAL POINT	15/148271	10042812
EXTENDED HEAT FRAME FOR PRINTED CIRCUIT BOARD	14/023521	9414524
OPERATION OF I/O IN A SAFE SYSTEM	14/219043	9747184
OPERATION OF I/O IN A SAFE SYSTEM	15/651023	10120772
SAFETY RELAY BOX SYSTEM	14/141580	9791901
TASK BASED VOTING FOR FAULT-TOLERANT FAIL SAFE COMPUTER SYSTEMS	14/141594	9311212
FAULT-TOLERANT FAILSAFE COMPUTER SYSTEM USING COTS COMPONENTS	14/140686	9665447
RELIABLE, LOW LATENCY HARDWARE AND SOFTWARE INTER-PROCESS COMMUNICATION CHANNEL FOR SAFETY CRITICAL SYSTEM	14/219051	9317359
VOTING ARCHITECTURE FOR SAFETY AND MISSION CRITICAL SYSTEMS	14/219057	9497099
MODULAR ELECTRONICS FOR CYLINDERS	14/490169	9288929
THERMAL CONDUCTION TO A CYLINDRICAL SHAFT	14/490186	10327357
ALIGNMENT MECHANISM FOR CABLING TO A CYLINDER HEAD	14/490226	9439312
DAISY-CHAIN FOR SAFETY SYSTEMS	15/624319	Pending
END TO END FPGA DIAGNOSTICS FOR A SAFETY SYSTEM	15/456034	10338995
FPGA MISMATCHED PACKET STOP FOR A SAFETY SYSTEM	15/455619	10372579
SIGNAL PAIRING FOR MODULE EXPANSION OF A FAILSAFE COMPUTING SYSTEM	15/700561	Pending
METHOD AND SYSTEM OF SYNCHRONIZING PROCESSORS TO THE SAME COMPUTATIONAL POINT	14/254930	9348657
DIRECT CONNECT ALGORITHM	14/251677	9367375
INTEGRATED THERMAL INSERTS AND COLD PLATE	13/741710	9713287
METHOD AND DEVICE TO PROVIDE UNIFORM COOLING IN RUGGED ENVIRONMENTS	13/757038	Pending